

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	618	substrat	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:00
L2	2	e and soft and hard near pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:01
L3	2	substrate and soft and hard near pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:01
L4	3	soft and hard near pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:01
S10	484	chip adj package near substrate	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:03
S11	1	chip adj package near substrate and milling and drilling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:05
S12	0	chip adj package near substrate and hard and soft near circuit and milling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:05
S13	0	chip adj package near substrate and soft near circuit and milling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:05
S14	6	chip adj package near substrate and milling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:06
S15	36	chip adj package near substrate and drilling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:10
S16	6	chip adj package near substrate and drilling and "29"/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:00

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	2	substrate and soft and hard near pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:01
L4	3	soft and hard near pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:05
L5	39	Chen near Huei.inv.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:24
L6	3	Chen near Huei near jen.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:26
L7	180	image adj sensing near chip	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:45
L8	1	image adj sensing near chip and soft near pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:46
L9	184810	image adj sensing near chip and flexible ear pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:46
L10	1	image adj sensing near chip and flexible near pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:46
S10	484	chip adj package near substrate	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:03
S11	1	chip adj package near substrate and milling and drilling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:05
S12	0	chip adj package near substrate and hard and soft near circuit and milling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:05

EAST Search History

S13	0	chip adj package near substrate and soft near circuit and milling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:05
S14	6	chip adj package near substrate and milling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:06
S15	36	chip adj package near substrate and drilling	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/28 17:10
S16	6	chip adj package near substrate and drilling and "29"/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 08:00